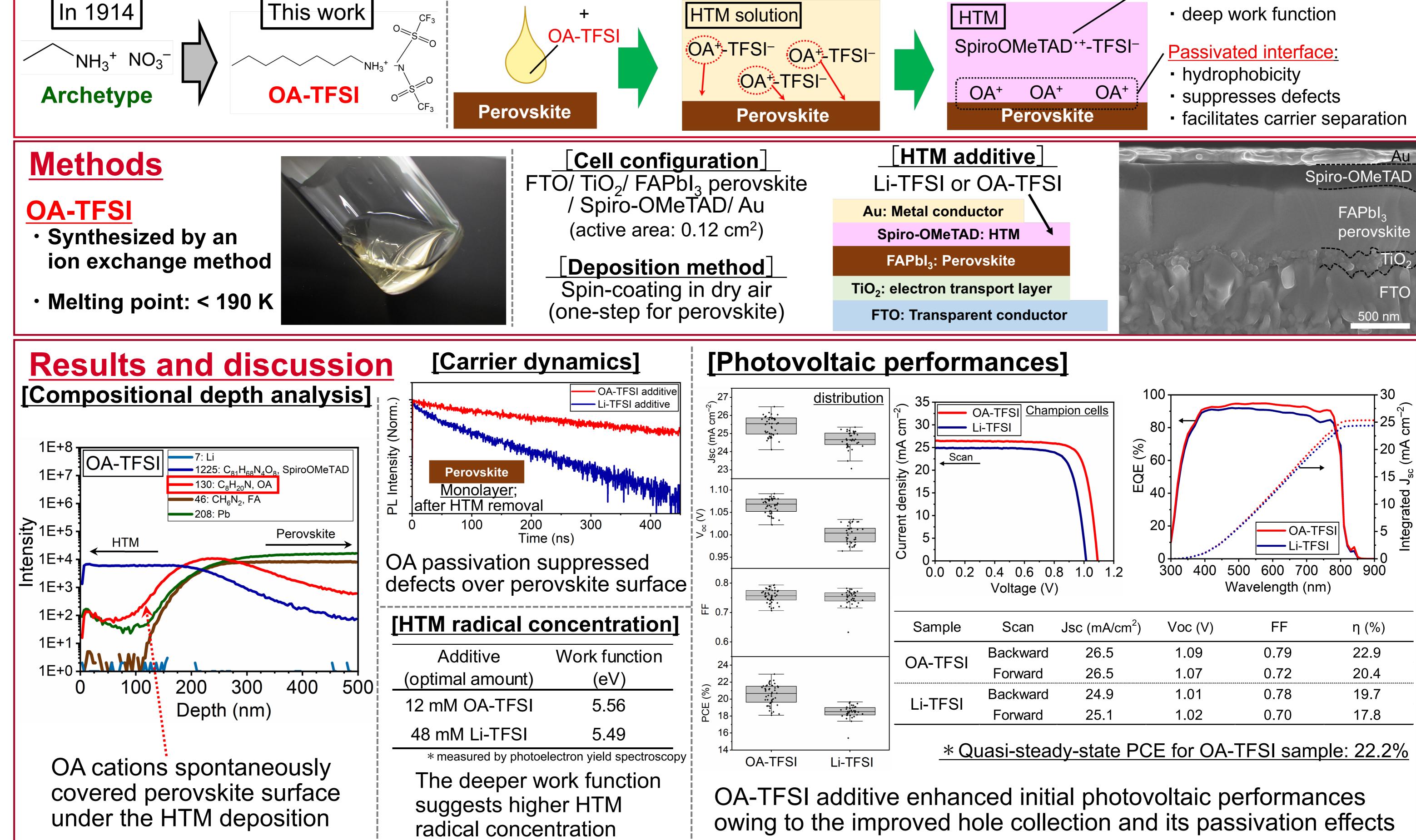
Aliphatic Primary Ammonium Bis(trifluoromethylsulfonyl)imide as a Highly Functional Additive for Hole Transport Material Layer in Perovskite Solar Cells

Introduction

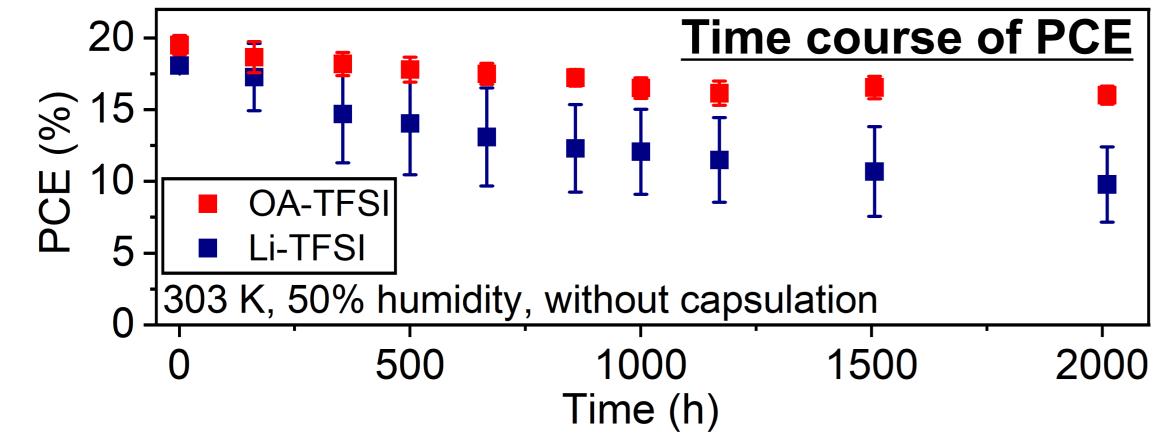
- Room-temperature ionic liquids (RTILs) based on bis(trifluoromethylsulfonyl)imide (TFSI) anion have been reported as promising Li-free additives for hole transport materials (HTMs) in perovskite solar cells (PCSs).
- However, cation designs of RTILs for PSC applications so far have been limited within currently major ones (e.g., imidazoles), so their functions have been confined particularly in controlling HTM/perovskite interface.
- In this work, an RTIL comprising an archetypal aliphatic primary ammonium (i.e., *n*-octylammonium: OA) and TFSI [1,2] is proposed and demonstrated as a highly functional additive for Spiro-OMeTAD HTM.

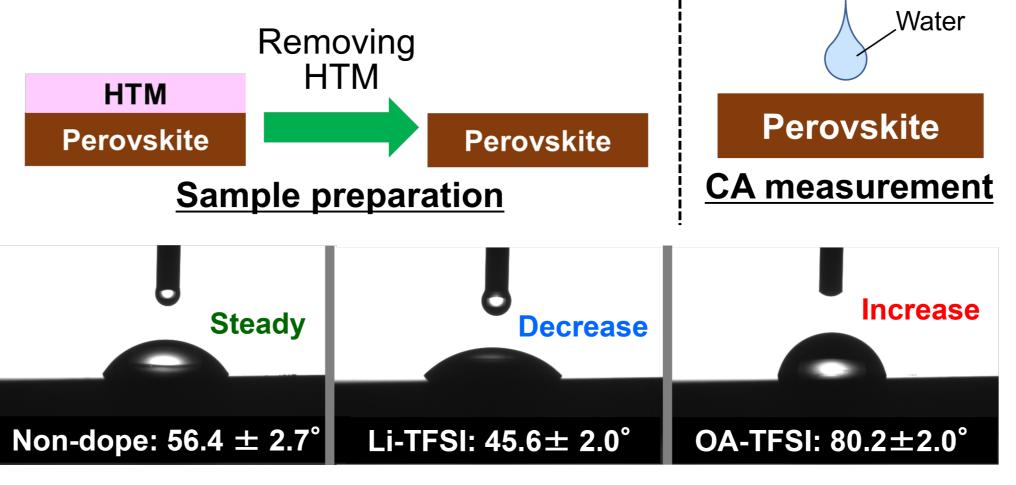
Spontaneous passivation HTM solution

Effective radical stabilization efficient carrier collection



[Hydrophobicity of perovskite surface]





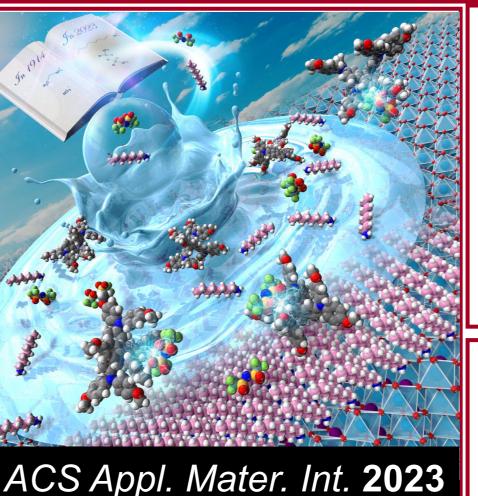
Pristine perovskite (before HTM deposition): 58.8± 1.3°

The spontaneous passivation by OA-TFSI rendered perovskite hydrophobic, and thereby improved long-time PCE stability in the presence of humidity



Conclusion

OA-TFSI exhibited crucial benefits simultaneously: (i) <u>spontaneous perovskite passivation</u> under HTM deposition process, and (ii) effective stabilization and generation of cationic Spiro-OMeTAD radicals, improving PCS performances involving their stability.



References

[1] N. Nishimura et al., *Chem Rxiv* **2023**, preprint, DOI: 10.26434/chemrxiv-2023-hsh8k.

[2] Y. Kim et al., Energy Environ. Sci. 2023, 16, 2226-2238.

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<u>Naoyuki Nishimura^{1*}, Hiroaki Tachibana¹, Ryuzi Katoh², Hiroyuki Kanda¹, Takurou N. Murakami¹</u>

1 National Institute of Advanced Industrial Science and Technology (AIST), Japan. 2 College of Engineering, Nihon University, Japan

